	© Copyright 2005. IPC international and Pan-J	sition Dec C, Bannockb American co	c laration ourn, Illinois. A opyright conve	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaration	tion of encom	the substances passes all lowe	within the er level mat	manufactur erials for wh	er listed it hich the m	tem. Note: if nanufacturer h	the item is an as has engineering	ssembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information					
upplier	Information														
Company name* Company unique ID				ique ID	Unique II			ique ID Authority				Response Date*			
nsemi												2025-06-08			
Contact Na	ame		Title - Contact				Phone - Contact*					Email - Contact*			
Product-E	Cnv-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorized	l Representative*	Title - Representative				Phone - Representative*				Email - Representative*					
roduct-E	Cnv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date	e Ve	Version Manufacturing Site		1	Weight*	UOM	Unit Type	
	MJ15003G BIP T03 NF			BIP T03 NPN 204	20A 140V FG		2025-06-08			MX5		1	11991.172	mg	Each
Ianufac	cturing Proccess Informati	on													
	Terminal Plating / Grid Array Mate	Cerminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperature		re Max T	Max Time at Peak Tempera		ure Numbe	r of Reflow Cy	cles			
SnAgCu (CU Alloy NA				0 C 30				seconds 3				
omments															
or more i	nformation regarding material co	mposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or [F] Optionally enter the positive (+				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	18.3	mg	Supplier	Silicon (Si)	7440-21-3		18.3	mg
Die Attach	795.56	mg	Supplier	Indium (In)	7440-74-6		39.778	mg
			Supplier	Silver (Ag)	7440-22-4		23.8668	mg
			А	Lead (Pb)	7439-92-1	7a	731.9152	mg
Lead Frame	11138.1	mg	В	Nickel (Ni)	7440-02-0		111.381	mg
			Supplier	Iron (Fe)	7439-89-6		11026.7188	mg
Plating	38.83	mg	Supplier	Silver (Ag)	7440-22-4		1.1649	mg
			Supplier	Tin (Sn)	7440-31-5		37.471	mg
			Supplier	Copper (Cu)	7440-50-8		0.1942	mg
Wire Bond - Al	0.382	mg	Supplier	Aluminum (Al)	7429-90-5		0.382	mg